



### SINGLE BUFFER GATE WITH 3-STATE OUTPUT

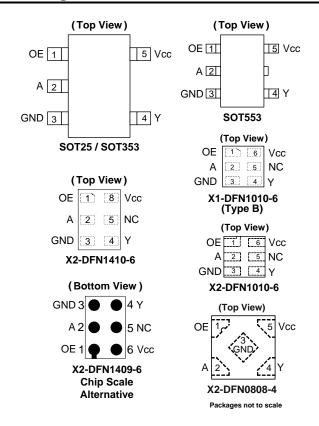
### **Description**

The 74LVC1G126 is a single non-inverting buffer/bus driver with a 3-state output. The output enters a high impedance state when a LOW-level is applied to the output enable (OE) pin. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using  $I_{\rm OFF}$ . The  $I_{\rm OFF}$  circuitry disables the output preventing damaging current backflow when the device is powered down.

#### **Features**

- Wide Supply Voltage Range from 1.65 to 5.5V
- ± 24mA Output Drive at 3.3V
- CMOS Low Power Consumption
- I<sub>OFF</sub> Supports Partial-Power-Down Mode Operation
- Inputs Accept Up to 5.5V
- ESD Protection Tested per JESD 22
  - Exceeds 200-V Machine Model (A115)
  - Exceeds 2000-V Human Body Model (A114)
  - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- Direct Interface with TTL Levels
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Pin Assignments**



## **Applications**

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as.
  - PCs, Networking, Notebooks, Netbooks, PDAs
  - Tablet Computers, E-Readers
  - Computer Peripherals, Hard Drives, CD/DVD ROM

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- TV, DVD, DVR, Set Top Box
- Cell Phones, Personal Navigation / GPS
- MP3 Players, Cameras, Video Recorders

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

-7: 7" Tape & Reel



## Ordering Information (Note 4)

T4 LVC1G 126 XXX -7

Logic Device Function Package Packing

74 : Logic Prefix LVC : 1.65 to 5.5 V Logic Family 1G : One Gate 126: 3-State Buffer OE active HIGH

W5 : SOT25 SE : SOT353 Z : SOT553 FS3 : X2-DFN0808-4

FW5 : X1-DFN1010-6 (Type B)

FW4 :X2-DFN1010-6 FX4 : X2- DFN1409-6 FZ4 : X2- DFN1410-6

Dort Number	Package	Package	Package	7" Tape	and Reel
Part Number	Code	(Notes 5 & 6)	Size	Quantity	Part Number Suffix
74LVC1G126W5-7	W5	SOT25	3.0mm x 2.8mm x 1.2mm 0.95 mm lead pitch	3,000/Tape & Reel	-7
74LVC1G126SE-7	SE	SOT353	2.0mm x 2.0mm x 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7
74LVC1G126Z-7	Z	SOT553	1.6mm x 1.6 mm x 0.62mm 0.5 mm lead pitch	4,000/Tape & Reel	-7
74LVC1G126FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8mm x 0.35mm 0.5 mm pad pitch (diamond)	5,000/Tape & Reel	-7
74LVC1G126FW5-7	FW5	X1-DFN1010-6 (Type B)	1.0mm x 1.0mm x 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G126FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G126FX4-7	FX4	X2-DFN1409-6 (Chip scale alternative)	1.4mm x 0.9mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G126FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7

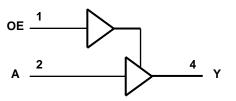
Notes:

- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.
- 5. Pad layout as shown on Diodes Inc. suggested pad layout which can be found on our website at http://www.diodes.com/package-outlines.html.
- 6. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Pin Descriptions**

Pin Name	Description
OE	Output Enable
Α	Data Input
GND	Ground
Y	Data Output
V <sub>CC</sub>	Supply Voltage
NC	No Connection

Logic	Diagram



## **Function Table**

Inp	Output	
OE	Α	Υ
Н	Н	Н
Н	L	L



## Absolute Maximum Ratings (Notes 7 & 8) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to +6.5	V
Vı	Input Voltage Range	-0.5 to +6.5	V
Vo	Voltage applied to output in high impedance or IOFF state	-0.5 to +6.5	V
Vo	Voltage applied to output in high or low state	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub>	Output Clamp Current	-50	mA
I <sub>O</sub>	Continuous output current	±50	mA
I <sub>CC</sub> , I <sub>GND</sub>	Continuous current through V <sub>CC</sub> or GND	±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

Notes:

## Recommended Operating Conditions (Note 9) (@TA = +25°C, unless otherwise specified.)

Symbol		Parameter	Min	Max	Unit
Vaa	Operating Voltage	Operating	1.65	5.5	V
Vcc	Operating voltage	Data retention only	1.5	15	V
	V <sub>IH</sub> High-Level Input Voltage	V <sub>CC</sub> = 1.65V to 1.95V	0.65 x V <sub>CC</sub>	_	
\/		V <sub>CC</sub> = 2.3V to 2.7V	1.7	_	\/
VIH		V <sub>CC</sub> = 3V to 3.6V	2	_	V
		V <sub>CC</sub> = 4.5V to 5.5V	0.7 x V <sub>CC</sub>	_	
		V <sub>CC</sub> = 1.65V to 1.95V	_	0.35 x V <sub>CC</sub>	
	Law Lavel Innut Valtage	V <sub>CC</sub> = 2.3V to 2.7V	_	0.7	.,,
$V_{IL}$	Low-Level Input Voltage	V <sub>CC</sub> = 3V to 3.6V	_	0.8	V
		V <sub>CC</sub> = 4.5V to 5.5V	_	0.3 x V <sub>CC</sub>	
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	Vcc	V
		V <sub>CC</sub> = 1.65V	_	-4	
		V <sub>CC</sub> = 2.3V	_	-8	
Lave	High-Level Output Current	V <sub>CC</sub> = 2.7V	_	-12	mA
Іон			_	-16	IIIA
		$V_{CC} = 3V$	_	-24	
		V <sub>CC</sub> = 4.5V	_	-32	
		V <sub>CC</sub> = 1.65V	_	4	
		V <sub>CC</sub> = 2.3V	_	8	
Les	Low-Level Output Current	V <sub>CC</sub> = 2.7V	_	12	mA
loL	Low-Level Output Current		_	16	IIIA
		V <sub>CC</sub> = 3V	_	24	
		V <sub>CC</sub> = 4.5V	_	32	
		V <sub>CC</sub> = 1.8V ± 0.15V, 2.5V ± 0.2V	_	20	
$\Delta t/\Delta V$	Δt/ΔV Input transition Rise or Fall Rate	V <sub>CC</sub> = 3.3V ± 0.3V	_	10	ns/V
		$V_{CC} = 5V \pm 0.5V$	_	5	
T <sub>A</sub>	Operating Free-Air Temperature	_	-40	+125	°C

Note: 9. Unused inputs should be held at  $V_{CC}$  or Ground.

<sup>7.</sup> Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device

operation should be within recommend values.

8. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.



## **Electrical Characteristics** (All typical values are at $V_{CC} = 3.3V$ , $T_A = +25$ °C)

Symbol	Daramatar	Test Conditions	v	-4	40°C to +85°	С	-40°C to	+125°C	Unit
Symbol	Parameter	rest Conditions	V <sub>CC</sub>	Min	Тур	Max	Min	Max	Unit
	I <sub>OH</sub> = -100μA	1.65V to 5.5V	V <sub>CC</sub> -0.1	_	_	V <sub>CC</sub> -0.1	_		
		$I_{OH} = -4mA$	1.65V	1.2	_	_	0.95	_	
		$I_{OH} = -8mA$	2.3V	1.9	_	_	1.7	_	
Vон	High Level Output Voltage	$I_{OH} = -12mA$	2.7V	2.2	_	_	1.9	_	V
	o aip air r oiliago	I <sub>OH</sub> = -16mA	3V	2.4	_	_	2.2	_	
		I <sub>OH</sub> = -24mA	3 V	2.3	_	_	2.0	_	
		I <sub>OH</sub> = -32mA	4.5V	3.8	_	_	3.4	_	
		I <sub>OL</sub> = 100μA	1.65V to 5.5V	_	_	0.1	_	0.1	
		I <sub>OL</sub> = 4mA	1.65V	_	_	0.45	_	0.7	
	Low Level Output Voltage	I <sub>OL</sub> = 8mA	2.3V	_	_	0.3	_	0.45	
$V_{OL}$		I <sub>OL</sub> = 12mA	2.7V	_	_	0.4	_	0.6	V
	Catput Voltage	I <sub>OL</sub> = 16mA	3V	_	_	0.4	_	0.6	
		I <sub>OL</sub> = 24mA		_	_	0.55	_	0.8	
		I <sub>OL</sub> = 32mA	4.5V	_	_	0.55	_	.8	
I <sub>I</sub>	Input Current	V <sub>I</sub> = 5.5V or GND	0 to 5.5V	_	± 0.1	±5	_	± 100	μΑ
l <sub>OFF</sub>	Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 5.5V	0V	_	_	±10	_	±200	μΑ
loz	Z State Leakage Current	V <sub>O</sub> =0 to 5.5V	3.6V	_	0.1	10	_	20	μА
Icc	Supply Current	V <sub>I</sub> = 5.5V or GND I <sub>O</sub> =0	5.5V	_	0.1	10	_	200	μА
Δl <sub>CC</sub>	Additional Supply Current	One input at V <sub>CC</sub> -0.6 V Other inputs at V <sub>CC</sub> or GND	3V to 5.5V	_	_	500	_	5,000	μΑ
Ci	Input Capacitance	$V_I = V_{CC} - \text{or GND}$	3.3V	_	5	_	_	_	pF

# Package Characteristics (All typical values are at V<sub>CC</sub> = 3.3V, T<sub>A</sub> = +25°C)

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	Min	Тур	Max	Unit
		SOT25		_	204	_	
		SOT353		_	371	_	
		SOT553		_	231	_	
0	Thermal Resistance	X2-DFN0808-4	(Note 10)	_	400	_	°C / / /
$\theta_{JA}$	Junction-to-Ambient	X1-DFN1010-6 (Type B)	(Note 10)	_	435	_	°C/W
		X2-DFN1010-6		_	445	_	
		X2-DFN1409-6		_	470	_	
		X2-DFN1410-6		_	460	_	
		SOT25		_	52	_	
		SOT353		_	143	_	
		SOT553		_	105	_	
0	Thermal Resistance	X2-DFN0808-4	(Note 10)	_	225	_	°C / / /
θυς	Junction-to-Case	X1-DFN1010-6 (Type B)	(Note 10)	_	250	_	°C/W
		X2-DFN1010-6		_	250	_	
		X2-DFN1409-6		_	275	_	
		X2-DFN1410-6		_	265	_	

Note: 10. Test condition for each of the 8 package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



# **Switching Characteristics**

Figure 1 Typical Values at  $T_A = +25$ °C and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V.

Parameter	From	То	V	T <sub>A</sub> :	= -40°C to +8	35°C	T <sub>A</sub> = -40°C	to +125°C	Unit		
i ai aiiietei	Input	Output	Vcc	Min	Тур	Max	Min	Max	Unit		
			1.8V ± 0.15V	1.0	3.0	8.0	1.0	10.5			
			2.5V ± 0.2V	0.5	2.1	5.5	0.5	7.0			
t <sub>pd</sub>	Α	Y	2.7V	0.5	2.3	5.5	0.5	7.5	ns		
			3.3V ± 0.3V	0.5	2.0	4.5	0.5	6.0			
			5.0V ± 0.5V	0.5	1.7	4.0	0.5	5.5			
			1.8V ± 0.15V	1.0	3.2	9.4	1.0	12.0			
		DE Y	2.5V ± 0.2V	0.5	2.2	6.6	0.5	8.5	ns		
t <sub>en</sub>	OE		2.7V	0.5	2.4	6.6	0.5	8.5			
					3.3V ± 0.3V	0.5	2.1	5.3	0.5	7.0	
			5.0V ± 0.5V	0.5	1.6	5.0	0.5	6.5			
			1.8V ± 0.15V	1.0	4.3	9.2	1.0	12.0			
			2.5V ± 0.2V	0.5	2.7	5.5	0.5	7.0			
t <sub>dis</sub> O	t <sub>dis</sub>	OE	Y	2.7V	0.5	3.4	5.5	0.5	7.0	ns	
			$3.3V \pm 0.3V$	0.5	3.0	5.5	0.5	7.0			
			5.0V ± 0.5V	0.5	2.2	4.2	0.5	5.5			

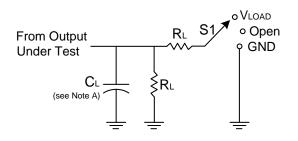
# **Operating Characteristics**

 $T_A = +25$ °C

	Parameter		Test Conditions	V <sub>CC</sub> = 1.8V Typ	V <sub>CC</sub> = 2.5V Typ	V <sub>CC</sub> = 3.3V Typ	V <sub>CC</sub> = 5V Typ	Unit
0	Power Dissipation	Outputs Enabled	f = 10 MHz	19	19	19	21	ρF
C <sub>pd</sub>	Capacitance	Outputs Disabled	I = IO WINZ	2	2	3	4	рг

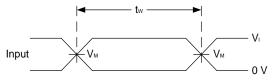


## **Parameter Measurement Information**

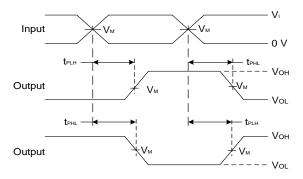


TEST	<b>S</b> 1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	$V_{LOAD}$
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

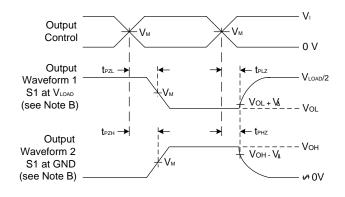
V	Inputs		V	V		В	<b>V</b> Δ
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	$R_L$	VA
1.8V±0.15V	Vcc	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	1kΩ	0.15V
2.5V±0.2V	Vcc	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	50pF	500Ω	0.3V



**Voltage Waveform Pulse Duration** 



**Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs** 



**Voltage Waveform Enable and Disable Times** Low and High Level Enabling

### Figure 1 Load Circuit and Voltage Waveforms

A. Includes test lead and test apparatus capacitance. Notes:

B. All pulses are supplied at pulse repetition rate ≤ 10MHz.
C. Inputs are measured separately one transition per measurement.

D. tpLz and tpHz are the same as tdis.

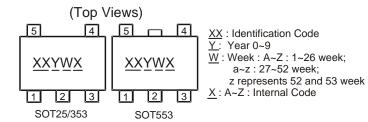
E. tpzL and tpzH are the same as tEN.

F. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>PD</sub>.



## **Marking Information**

### (1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G126W5-7	SOT25	UZ
74LVC1G126SE-7	SOT353	UZ
74LVC1G126Z-7	SOT553	UZ

### (2) DFN Packages

(Top View) XX: Identification Code

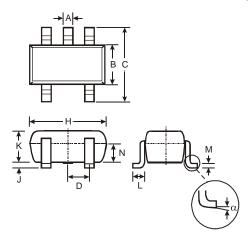
XX  $\underline{Y} \underline{W} \underline{X}$  \(\frac{\text{Y}}{2}\): Year 0-9
\(\frac{\text{Y}}{2}\): Week: A-Z: 1~26 week;
\(a \sim z : 27~52 \) week;
\(z \) represents 52 and 53 week
\(\frac{\text{X}}{2}\): A-Z: Internal Code

Part Number	Package	Identification Code
74LVC1G126FS3-7	X2-DFN0808-4	WZ
74LVC1G126FW5-7	X1-DFN1010-6 (Type B)	VZ
74LVC1G126FW4-7	X2-DFN1010-6	UZ
74LVC1G126FX4-7	X2-DFN1409-6	MY
74LVC1G126FZ4-7	X2-DFN1410-6	UZ



Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOT25

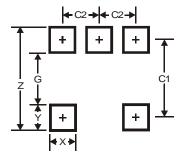


SOT25			
Dim	Min	Max	Тур
Α	0.35	0.50	0.38
В	1.50	1.70	1.60
C	2.70	3.00	2.80
ם	-	1	0.95
Ξ	2.90	3.10	3.00
7	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
М	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOT25

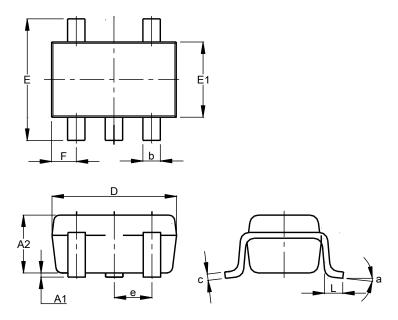


Dimensions	Value
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95



Please see http://www.diodes.com/package-outlines.html for the latest version.

### **SOT353**

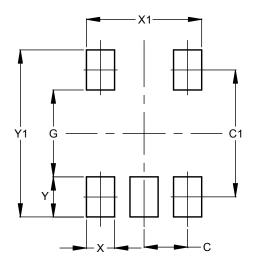


SOT353				
Dim	Min	Max	Тур	
A1	0.00	0.10	0.05	
A2	0.90	1.00	1.00	
b	0.10	0.30	0.25	
С	0.10	0.22	0.11	
D	1.80	2.20	2.15	
Е	2.00	2.20	2.10	
E1	1.15	1.35	1.30	
е	0.650 BSC			
F	0.40	0.45	0.425	
L	0.25	0.40	0.30	
а	0°	8°		
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### **SOT353**

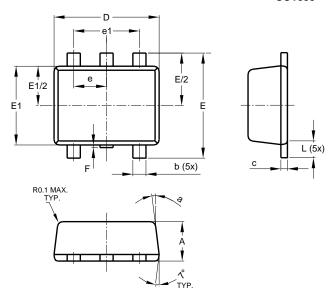


Dimensions	Value	
פווטופוושוווט	(in mm)	
C	0.650	
C1	1.900	
G	1.300	
X	0.420	
X1	1.720	
Y	0.600	
Y1	2.500	



Please see http://www.diodes.com/package-outlines.html for the latest version.

### **SOT553**

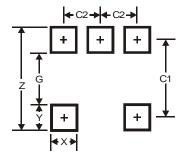


SOT553			
Dim	Min	Max	Тур
Α	0.55	0.62	0.60
b	0.15	0.30	0.20
U	0.10	0.18	0.15
D	1.50	1.70	1.60
Е	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50 BSC		$\circ$
e1	1.00 BSC		
F	0.00	0.10	
L	0.10	0.30	0.20
а	6°	8°	7°
All Dimensions in mm			

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOT553

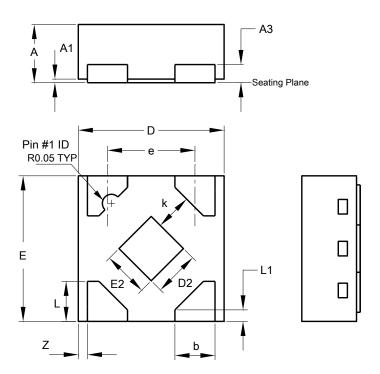


Dimensions	Value
Z	2.2
G	1.2
Х	0.375
Υ	0.5
C1	1.7
C2	0.5



Please see http://www.diodes.com/package-outlines.html for the latest version.

### X2-DFN0808-4

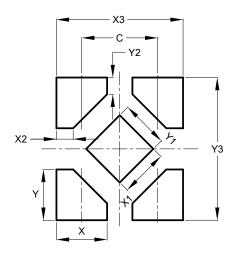


X2-DFN0808-4			
Dim	Min	Max	Тур
Α	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
е	-	-	0.48
k	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
z	-	-	0.05
All Dimensions in mm			

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN0808-4

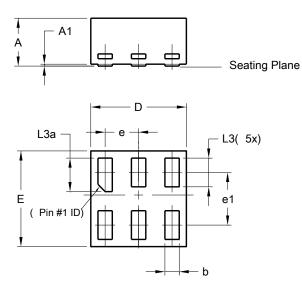


Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
Х3	0.800
Υ	0.320
Y1	0.300
Y2	0.106
Y3	0.900



Please see http://www.diodes.com/package-outlines.html for the latest version.

### X1-DFN1010-6 (Type B)

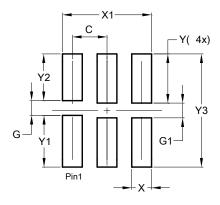


X1-DFN1010-6			
	(Ty	pe B)	
Dim	Min	Max	Тур
Α	ı	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
Е	0.95	1.050	1.00
е	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X1-DFN1010-6 (Type B)

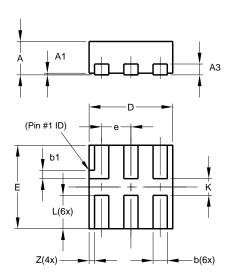


Dimensions	Value
Dilliensions	(in mm)
С	0.350
G	0.150
G1	0.150
Х	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1 150



Please see http://www.diodes.com/package-outlines.html for the latest version.

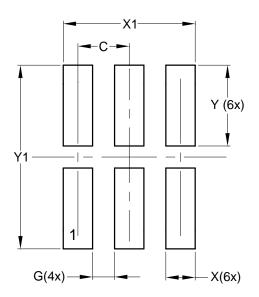
### X2-DFN1010-6



X2-DFN1010-6			
Dim	Min	Max	Тур
Α		0.40	0.39
A1	0.00	0.05	0.02
A3			0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
Е	0.95	1.05	1.00
е			0.35
L	0.35	0.45	0.40
K	0.15		
Z			0.065
All Dimensions in mm			

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



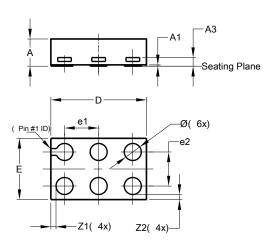
### X2-DFN1010-6

Dimensions	Value (in mm)	
С	0.350	
G	0.150	
Х	0.200	
X1	0.900	
Y	0.550	
Y1	1.250	



Please see http://www.diodes.com/package-outlines.html for the latest version.

### X2-DFN1409-6 CHIP SCALE ALTERNATIVE

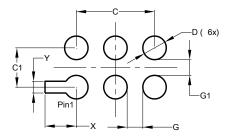


	X2-DFN1409-6			
Dim	Min	Max	Тур	
Α	-	0.40	0.39	
A1	0	0.05	0.02	
A3	1	-	0.13	
Ø	0.20	0.30	0.25	
D	1.35	1.45	1.40	
Е	0.85	0.95	0.90	
e1	-	ı	0.50	
e2	-	-	0.50	
<b>Z</b> 1	1	-	0.075	
Z2	-	-	0.075	
All Dimensions in mm				

## **Suggested Pad Layout**

 $\label{please} Please see \ http://www.diodes.com/package-outlines.html \ for the latest version.$ 

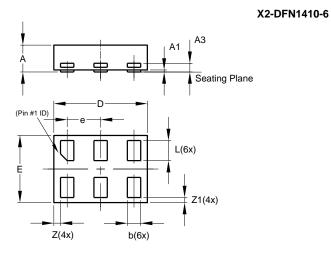
### X2-DFN1409-6 CHIP SCALE ALTERNATIVE



Dimensions	Value	
Difficusions	(in mm)	
С	1.000	
C1	0.500	
D	0.300	
G	0.200	
G1	0.200	
X	0.400	
Υ	0.150	



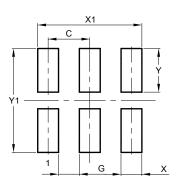
Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1410-6			
Dim	Min	Max	Тур
Α		0.40	0.39
A1	0.00	0.05	0.02
A3		_	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
Е	0.95	1.05	1.00
е			0.50
L	0.25	0.35	0.30
Z		_	0.10
<b>Z</b> 1	0.045	0.105	0.075
All Dimensions in mm			

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



### X2-DFN1410-6

Dimensions	Value (in mm)
С	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250



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